



69



Square interface connectors (page 18)



23

DEPARTMENTS

	AEI NEWS	8
	IN VIEW THIS MONTH	10
	BUSINESS STRATEGY	56
	PRODUCT NEWS	71

ASIA ELECTRONICS INDUSTRY (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3445-6890. Editorial e-mail: may@dempa.co.jp;

Subscription e-mail: circulationmanila@dempa.co.jp. The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at <http://aei.dempa.net/paidsub/subscription.html>

Send address corrections to Dempa Publications, Inc., c/o Quantum Solutions (HK) Ltd. Unit 3-6, G/F Pacific Trade Centre, 2 Kai Hing Road, Kowloon Bay, Kowloon, Hong Kong

TAIWAN: International Dempa Trade Co. Ltd., 7F, No. 34, Sec. 1, Nanjing East Road., Taipei, Taiwan 104 Tel: +886-2-2563 4595 Fax: +886-2-2567-5559
KOREA: Dempa Publications, Seoul Office, Masters Tower, Room 1404, 553 Dohwa-dong, Mapo-ku, Seoul, Korea, 121-040, Tel: +82-2-714-2983 Fax: +82-2-714-2984
PHILIPPINES: Dempa Publications, Inc. - Regional Headquarters, Herrera Tower, Room 2510, 98 V.A. Rufino Street, Salcedo Village, Makati City, Philippines, Tel: +63-2-845-0906 Fax: +63-2-845-1829

President & Publisher: Tetsuo Hirayama
 Copyright © 2017 by Dempa Publications, Inc.

All rights reserved. The contents of this magazine may not be reproduced in whole or in part without the prior permission of the copyright owner. Printed in Hong Kong.

SPECIAL REPORT

NI Outlines Test Challenges to Propel 5G Deployment	12
Various Fields Pull up Connectors Market	16
Foundry Service for Prototyping Integrated Heterogeneous Device Module by Minimal Fab	21

TECH FOCUS

Higher Image Quality Displays Up the Ante in Post-LCD Race	22
Circuit Protection Components Rise up to Shield Advanced Electronics	25
Lithium-Ion Battery Monitoring LSI Doubles up on Safety	27
Lightning Surge Protection Device Promotes Fail-Safe Equipment	31
SIGFOX-Compliant Wireless Module Emerges in IoT Network	35

SMT's: IN REVIEW

38

TEST AND MEASUREMENT

42

TECHNOLOGY HIGHLIGHT

RF Sputtering Yields Novel GaN Piezoelectric Thin Film	44
Sprintrionics Creates Highly Sensitive Sensor Elements for IoT	46
AIST, Arakawa Employ Aerosol Deposition in Ceramic Film Coating	47
Property Control Lifts Energy Harvesting Efficiency of Ferroelectric Materials	49

PRODUCT HIGHLIGHT

Highly Sensitive Film Sensor Permits Large, Curved Car Displays	51
---	----

INDUSTRY REPORT

52

ZOOM-IN

55

MANUFACTURING FRONT

Nippon Mektron Carries out Integrated FPC Production in Thailand	57
--	----

SHOW PREVIEW

HKPCA & IPC Show 2017	58
-----------------------	----

SHOW REPORT

NEPCON South China 2017	60
SEMICON Taiwan 2017	66
electronica and productronica India 2017	68